Title (en)

Manufacturing method for sliding contact for medium and high current

Title (de)

Verfahren zur Herstellung eines Gleitkontaktstücks für mittlere bis hohe Stromdichten

Title (fr)

Procédé de fabrication pour contact glissant pour courants forts et moyens

Publication

EP 1329993 A3 20051221 (DE)

Application

EP 02026559 A 20021128

Priority

DE 10201923 A 20020119

Abstract (en)

[origin: EP1329993A2] The process involves warm premixing graphite and plastic binder and cold mixing the resulting premixture with copper. The resulting main mixture is pressed into a sliding contact piece and sintered. During the premixing of graphite and plastic binder, a metal is selected from the group consisting of zinc, tin, and bismuth to add an alloy of the combination. An Independent claim is also included for a sliding contact piece.

IPC 1-7

H01R 39/20; H01R 43/12

IPC 8 full level

B22F 3/10 (2006.01); **B22F 5/00** (2006.01); **C22C 1/04** (2006.01); **H01R 39/20** (2006.01); **H01R 43/12** (2006.01); **H02K 13/00** (2006.01)

CPC (source: EP US)

H01R 39/20 (2013.01 - EP US); **H01R 43/12** (2013.01 - EP US); Y10T 29/49009 (2015.01 - EP US); Y10T 29/49119 (2015.01 - EP US); Y10T 29/53143 (2015.01 - EP US); Y10T 428/12146 (2015.01 - EP US)

Citation (search report)

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Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR IE IT LI LU MC NL PT SE SK TR

DOCDB simple family (publication)

EP 1329993 A2 20030723; **EP 1329993 A3 20051221**; **EP 1329993 B1 20080102**; AT E382969 T1 20080115; DE 10201923 A1 20030807; DE 10201923 B4 20060524; DE 50211452 D1 20080214; JP 2003272795 A 20030926; JP 4073319 B2 20080409; US 2003135993 A1 20030724; US 2009029184 A1 20090129; US 7449144 B2 20081111

DOCDB simple family (application)

EP 02026559 A 20021128; AT 02026559 T 20021128; DE 10201923 A 20020119; DE 50211452 T 20021128; JP 2003009275 A 20030117; US 28408108 A 20080918; US 34682403 A 20030117